

PRODUCT END-OF-LIFE DISASSEMBLY INSTRUCTIONS

Product Category: Personal Computers

Marketing Name / Model

Lanix Corp 6020

Purpose: The document is intended for use by end-of-life recyclers. It provides the instructions for the disassembly of Lanix products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	Mother Board, SSD, RAM, Power supply, External Keyboard (KB), External Mouse	4
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	RTC/CMOS Battery	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)		
Mercury-containing components		
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Panel LCD	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	AC Power cord	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner		
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where component and materials requiring selective treatment can be removed.

Tool Description	Tool Size (If applicable)
#1 Screwdriver	PHILLIPS PH2
#2 Screwdriver	PHILLIPS PH3

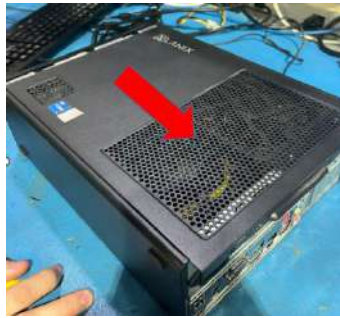
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure. For End-of-Life product disassembly instructions of external accessories including external keyboard (KB), external Power Supply (EPS), external cables and cords, and external mouse refer to the following URL: End-of-Life Product Disassembly Instructions (lanix.com)

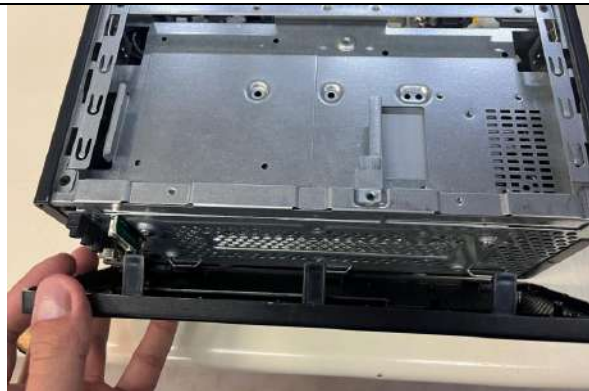
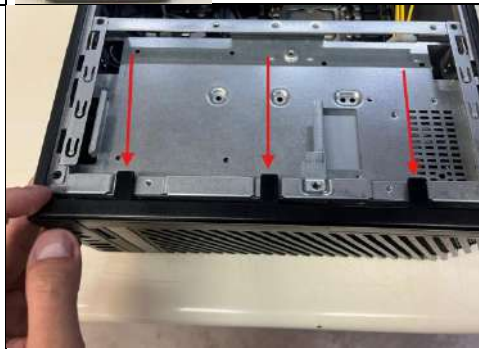
1. Remove Top Cover from the case.
2. Remove Bottom Cover from the case.
3. Remove Front Panel.
4. Remove the screws and Remove the Case Panel.
5. Remove the screws and Remove Fan.
6. Remove the PSU Power connector from the Motherboard.
7. Remove the motherboard screws and remove the motherboard from the case.
8. Remove the screw from the SSD and remove the SSD.
9. Remove Memory.
10. Remove the CPU cooler screws and remove the CPU cooler from the case.
11. Remove the CPU cooler power connector.
12. Press the CPU holder and remove the CPU.

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit.

1. Removed
Top Cover
from Case
tool less
(hand screw)



2. Removed
Front Panel
is tool less
(hand screw)



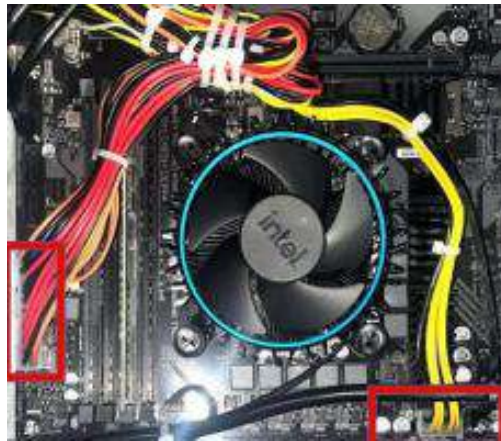
3. Removed
the screw
and
Removed the
Case Panel
with Phillips
PH2



4. Removed
Motherboard
with Phillips
PH3



5. Removed
the PSU
Power
connector
from the
Motherboard
tool less



5. Removed
Main Fan
with Phillips
PH2



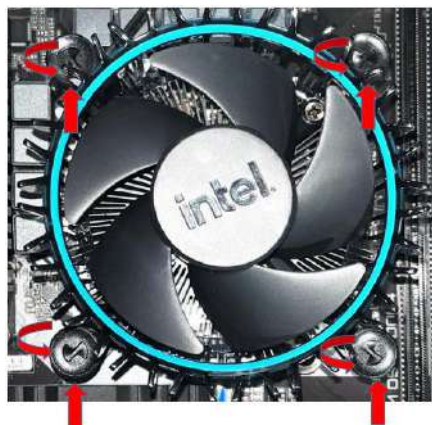
6. Removed
SDD with
Phillips PH2



7. Removed
RAM and
RTC battery
tool less



8. Remove
the CPU
cooler
screws and
remove the
CPU Cooler



3.2 Location of components requiring selective treatment.

